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## CONTENTS

Special Issue on 28th Symposium on "Microjoining and Assembly Technology in Electronics" (Mate2022
S.P.S.Announcement N20
Preface
Special issue on "Mate 2022"  Akira YAMAUCHI 181
Research Papers
Effect of Gallium Addition on High-Temperature Deformation Behavior of Tin Naoyuki HAMADA 182
Growth Kinetics of Reaction Layer Formed on Boundary between Sn-58Bi Solder and Probe Pin for Semiconductor Package Test Kazumi WATARAI, Ikuo SHOHJI, Tatsuya KOBAYASHI, Tomohisa HOSHINO,
Kenichi SATO, Shunsuke KOBAYASHI and Naohito ODANI 188
Effect of Added Element on Power Cycle Damage Behavior of Die Bonded Joints with Sn-Sb-Ag Solder
Yuta YAMANAKA, Ikuo SHOHJI, Tatsuya KOBAYASHI, Kohei MITSUI and Hirohiko WATANABE 194
Visualization of Joint Behavior during Ultrasonic Flip Chip Bonding Using In-Situ Strain Monitoring Method
Keiko IKUTA, Kiyokazu ITOI, Kei TSUNEMASA, Daisuke SAKURAI and Tanemasa ASANO 202
Method and Characteristics of Silicon Anisotropic Wet Etching
Using Low Concentration Alkaline Droplets Hiroshi TANAKA, Takumi NAGASAWA and Yuuto KAWAHARA 209
Mechanism and Countermeasures for High-Temperature Enclosed Electrochemical Migration Akiko TAKAKI, Ai ASAMI, Hisahiko YOSHIDA and Haruya SAKUMA 215
Substrate Wiring Formation by Imprinting Technology Using a Soft Replica Hiroshi KOMATSU, Daisuke SAKAI and Nozomi SHIMOISHIZAKA 221
Study for Cu-Cu Bonding Technology by Nanoporous Cu Structure Daiki FURUYAMA, Junta INOUE, Takuma NAKAGAWA, Koji TATSUMI, Sho NAKAGAWA and Takuma KATASE 227
Development of Squeegee Shape Which Has a Superior Continuous Printability by Stabilizing the Paste Roll Behavior
Masanao YAMASAKI 233
Defect Suppression by Polymer Additive in Si Microfabrication Using Metal Assisted Chemical Etching
Mitsuo SANO, Susumu OBATA, Takayuki TAJIMA, Yasunari UKITA, Kazuhito HIGUCHI, Ayumu MATSUMOTO and Shinji YAE 239
The Investigation of Bonding Reliability Improvement for Power Module Containing Sintered Ag
Tsuyoshi TANIGAKI and Yuki KAWAMURA 246
Effect of Convex Structure Formation Using Cold Spray Method on Copper / Epoxy Resin Bond Strength
Michiya MATSUSHIMA, Naoki TSUJI, Shotaro OGURA and Shinji FUKUMOTO 253
Effect of Chemical Factors on Interfacial Electrical Resistivity Between Flexible Electrically Conductive Adhesives and Metal Electrodes Takanori FUKUSHIMA and Masahiro INOUE 260
Special Report for Mate 2022
Report on 28th Symposium on "Microjoining and Assembly Technology in Electronics"  Michiya MATSUSHIMA 267
S.P.S.News N22